Application No.: 10/822,695

AMENDMENTS TO THE CLAIMS:

Please amend the claims as follows:

1. (Currently amended) A method for producing conductive particles comprising the

steps of:

introducing a solution composed mainly of palladium chloride and hydrochloric acid into

an electroless plating bath containing particles of an organic material or an inorganic material

while stirring said bath; and

simultaneously applying an electroless plating to the surface of said particles and

allowing the palladium catalyst to be carried on the surface of said particles to give conductive

particles having an electroless plate coating,

wherein said electroless plate coating comprises at least one selected from the group

consisting of Ni, Ni-P, Ni-B, Cu, an Ni-PTFE composite coating and a Cu-PTFE composite

coating.

2. (Original) The method for producing conductive particles in accordance with claim 1,

wherein said solution has a palladium chloride concentration of 0.3 to 10 g/L.

3. (Original) The method for producing conductive particles in accordance with claim 1,

wherein said electroless plate coating has three-dimensionally connected pores that allow water

molecules, hydroxy ions, sodium ions or potassium ions to pass through and diffuse.

4

Application No.: 10/822,695

4. (Original) The method for producing conductive particles in accordance with claim 1, wherein said inorganic material comprises at least one selected from the group consisting of Cu, Ni, Al, Fe, Ag, Mo and W or any alloy thereof.

5. (Original) The method for producing conductive particles in accordance with claim 1, wherein said inorganic material comprises at least one selected from the group consisting of Al₂O₃, SiO₂, Ni(OH)₂ and Ca(OH)₂.

6. (Cancelled)